

CUTBACK ASPHALT Product Data Sheet

CHEMIX MC-30

Chemix MC-30 is a high performing medium curing cutback asphalt that meets the highest requirements for modern high-performance pavements. Consistent with its high performance, Chemix MC-30 is produced to high standards with stringent quality control.

Chemix MC-30 cutback asphalt is primarily suited for applications where medium curing rate is required. Typical applications are prime coating, tack coating of dusty substrates, open-graded cold-mix.

Chemix MC-30 specifications

Test	Unit	Test Method	Specification
Viscosity at 60°C	mm²/s	ASTM D-2170	30 - 60
Flash point, (TAG open-cup), min	°C	ASTM D-3143	38
Distillate test, volume % of total distillate to 360 °C:		ASTM D-402	
to 225°C, max	%	ASTM D-402	25
to 260°C	%	ASTM D-402	40 - 70
to 316°C	%	ASTM D-402	75 - 93
Residue from distillation to 360°C, vol. min	%	ASTM D-402	50
Test on residue from distillation		ASTM D-402	
Viscosity at 60°C	Stokes	ASTM D-2170	300 - 1200
Ductility at 25°C, min	cm	ASTM D-113	100
Solubility in trichloroethylene, min	%	ASTM D-2042	99.0
Water content, max	%	ASTM D-95	0.2

Packaging and storage

Chemix MC-30 can be delivered in 200 liters drums or in 20 tons bulk liquid container – BLC. Drums should be stored in a well-ventilated place. There is no limit of time for storing and keeping Chemix MC-30, provided the drums are stored horizontally in a dry and well-ventilated place.

Recommendation for application

Chemix MC-30 is a homogeneous petroleum binder. It is however always recommended rolling the drums back and forth a few times before use. Caution should be exercised when opening the drum lid as some differential pressure might have built-up inside of the drum from the time it was filled to the time it is opened. Due to its relatively low viscosity, Cosmic MC-30 is ready to use and does not require any heating prior to spraying. It is advisable to spray, as evenly as possible, Chemix MC-30 on dry stones or substrates in order to promote a complete binder-aggregate adhesion.

The information contained herein is believed to be accurate at the time of printing, but no warranty is given neither is freedom from any patent to be inferred.